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substrate between them is formed in the shape in which a part is hollowed out so that a part opposite to the conductor is included.

Page 7, fifth, sixth and seventh full paragraphs (lines 14-22), replace the paragraphs with:

Figs. 5A and 5B are an exploded view and a sectional view showing a high frequency circuit module equivalent to a second embodiment of the invention;

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Figs. 6A and 6B are an exploded view and a sectional view showing a high frequency circuit module equivalent to a third embodiment of the invention;

Figs. 7A and 7B are an exploded view and a sectional view showing a high frequency circuit module equivalent to a fourth embodiment of the invention;

IN THE CLAIMS

Please rewrite claims 3, 4, 7 and 8 and add new claims 17-26 as set forth below.

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3. (Amended) A high frequency circuit module provided with a first dielectric substrate on which a semiconductor element and matching circuits on the input side and on the